

TOSHIBA Bipolar Linear Integrated Circuit Silicon Monolithic

# TA8277HQ

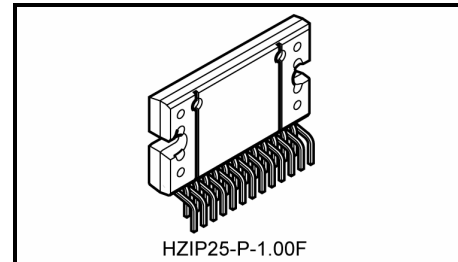
## Max Power 43 W BTL × 4 ch Audio Power IC

The TA8277HQ is 4 ch BTL audio power amplifier for car audio application.

This IC can generate more high power:  $P_{OUTMAX} = 43\text{ W}$  as it is included the pure complementary PNP and NPN transistor output stage.

It is designed low distortion ratio for 4 ch BTL audio power amplifier, built-in stand-by function and muting function.

Additionally, the AUX amplifier and various kind of protector for car audio use is built-in.



Weight: 7.7 g (typ.)

### Features

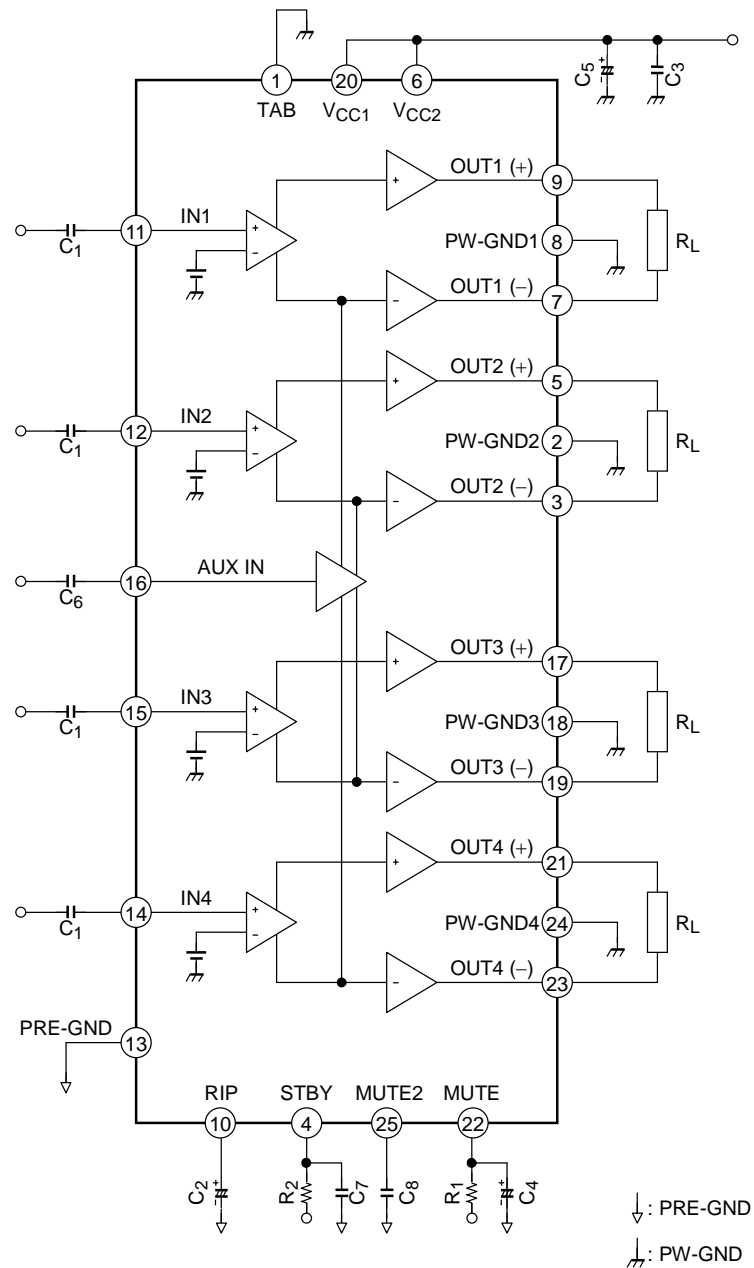
- High power:  $P_{OUTMAX} (1) = 43\text{ W}$  (typ.)  
     ( $V_{CC} = 14.4\text{ V}$ ,  $f = 1\text{ kHz}$ , JEITA max,  $R_L = 4\ \Omega$ )  
     :  $P_{OUTMAX} (2) = 40\text{ W}$  (typ.)  
     ( $V_{CC} = 13.7\text{ V}$ ,  $f = 1\text{ kHz}$ , JEITA max,  $R_L = 4\ \Omega$ )  
     :  $P_{OUT} (1) = 28\text{ W}$  (typ.)  
     ( $V_{CC} = 14.4\text{ V}$ ,  $f = 1\text{ kHz}$ , THD = 10%,  $R_L = 4\ \Omega$ )  
     :  $P_{OUT} (2) = 24\text{ W}$  (typ.)  
     ( $V_{CC} = 13.2\text{ V}$ ,  $f = 1\text{ kHz}$ , THD = 10%,  $R_L = 4\ \Omega$ )
- Low distortion ratio: THD = 0.02% (typ.)  
     ( $V_{CC} = 13.2\text{ V}$ ,  $f = 1\text{ kHz}$ ,  $P_{OUT} = 5\text{ W}$ ,  $R_L = 4\ \Omega$ )
- Low noise:  $V_{NO} = 0.10\text{ mVrms}$  (typ.)  
     ( $V_{CC} = 13.2\text{ V}$ ,  $R_g = 0\ \Omega$ ,  $G_V = 26\text{ dB}$ ,  $BW = 20\text{ Hz} \sim 20\text{ kHz}$ )
- Built-in stand-by switch function (pin 4)
- Built-in muting function (pin 22)
- Built-in AUX amplifier from single input to 4 channels output (pin 16)
- Built-in various protection circuit
  - : Thermal shut down, over voltage, out to GND, out to  $V_{CC}$ , out to out short
- Operating supply voltage:  $V_{CC} (opr) = 9 \sim 18\text{ V}$

Note 1: Install the product correctly. Otherwise, it may result in break down, damage and/or degradation to the product or equipment.

Note 2: These protection functions are intended to avoid some output short circuits or other abnormal conditions temporarily. These protect functions do not warrant to prevent the IC from being damaged.

- In case of the product would be operated with exceeded guaranteed operating ranges, these protection features may not operate and some output short circuits may result in the IC being damaged.

## Block Diagram



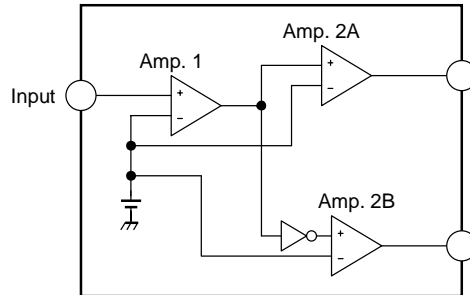
Note3: Some of the functional blocks, circuits, or constants in the block diagram may be omitted or simplified for explanatory purpose.

## Caution and Application Method

(Description is made only on the single channel.)

### 1. Voltage Gain Adjustment

This IC has no NF (negative feedback) terminals. Therefore, the voltage gain can't be adjusted, but it makes the device a space and total costs saver.



**Figure 1 Block Diagram**

The voltage gain of Amp.1 :  $G_{V1} = 0 \text{ dB}$

The voltage gain of Amp.2A, B :  $G_{V2} = 20 \text{ dB}$

The voltage gain of BLT Connection :  $G_V \text{ (BTL)} = 6 \text{ dB}$

Therefore, the total voltage gain is decided by expression below.

$$G_V = G_{V1} + G_{V2} + G_V \text{ (BTL)} = 0 + 20 + 6 = 26 \text{ dB}$$

### 2. Stand-by SW Function (pin 4)

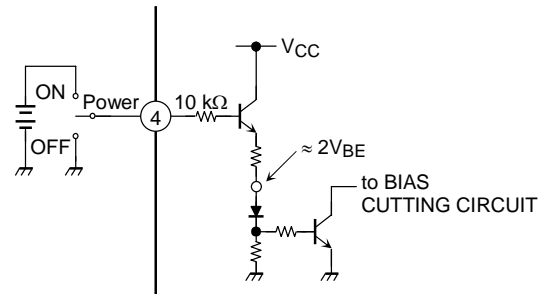
By means of controlling pin 4 (stand-by terminal) to high and low, the power supply can be set to ON and OFF. The threshold voltage of pin 4 is set at about  $3V_{BE}$  (typ.), and the power supply current is about  $2 \mu\text{A}$  (typ.) at the stand-by state.

#### Control Voltage of pin 4: $V_{SB}$

Stand-by	Power	$V_{SB}$ (V)
ON	OFF	0~1.5
OFF	ON	$3-V_{CC}$

#### Adjustage of Stand-by SW

- (1) Since  $V_{CC}$  can directly be controlled to ON or OFF by the microcomputer, the switching relay can be omitted.
- (2) Since the control current is microscopic, the switching relay of small current capacity is satisfactory for switching



**Figure 2 With pin 4 set to High, Power is turned ON**

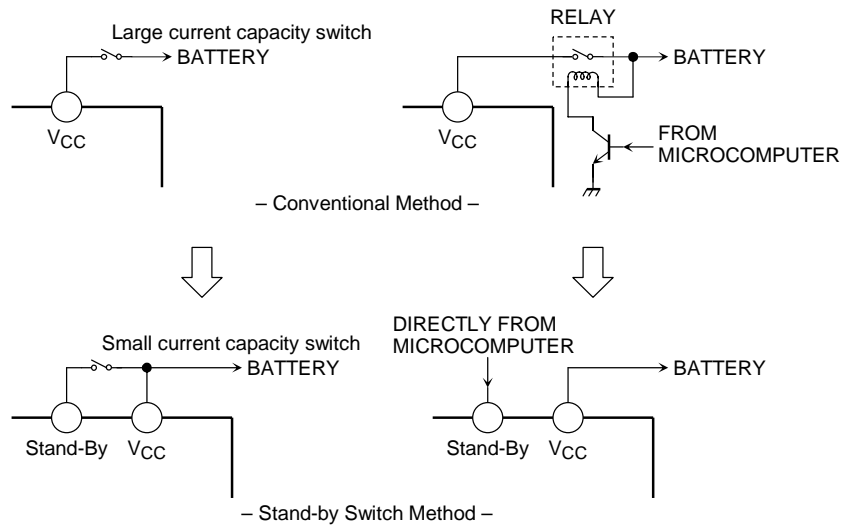


Figure 3

**3. Muting Function (pin 22)**

By means of controlling pin 22 less than 0.5 V, it can make the audio muting condition.

The muting time constant is decided by R<sub>1</sub>, C<sub>4</sub> and C<sub>8</sub> and these parts is related the pop noise at power ON/OFF.

The series resistance; R<sub>1</sub> must be set up less than 5 kΩ.

The muting function have to be controlled by a transistor, FET and μ-COM port which has I<sub>MUTE</sub> > 50 μA ability.

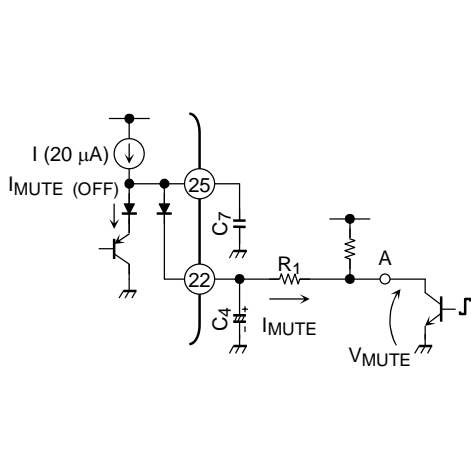


Figure 4 Muting Function

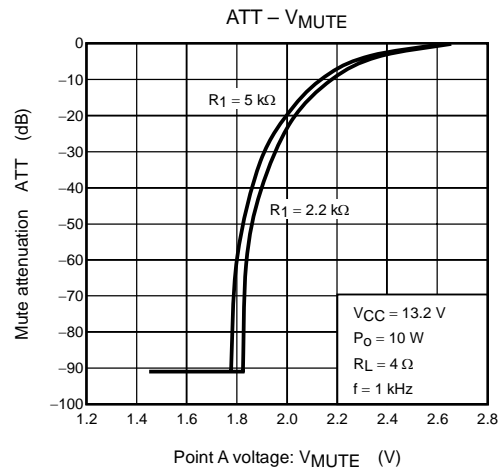


Figure 5 Mute Attenuation – V<sub>MUTE</sub> (V)

**4. AUX Input (pin 16)**

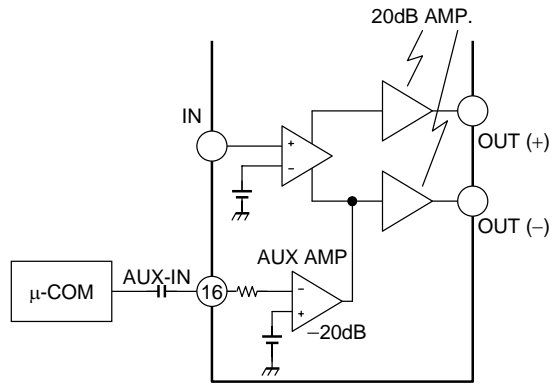
The pin 16 is for input terminal of AUX amplifier.

The total gain is 0dB by using of AUX amplifier.

Therefore, the  $\mu$ -COM can directly drive the AUX amplifier.

BEEP sound or voice synthesizer signal can be input to pin 16 directly.

When AUX function is not used, this pin must be connected to PRE-GND (pin 13) via a capacitor.



**Figure 6 AUX Input**

## Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Peak supply voltage (0.2 s)	V <sub>CC</sub> (surge)	50	V
DC supply voltage	V <sub>CC</sub> (DC)	25	V
Operation supply voltage	V <sub>CC</sub> (opr)	18	V
Output current (peak)	I <sub>O</sub> (peak)	9	A
Power dissipation	P <sub>D</sub> (Note4)	125	W
Operation temperature	T <sub>opr</sub>	-40~85	°C
Storage temperature	T <sub>stg</sub>	-55~150	°C

Note 4: Package thermal resistance  $\theta_{j-T} = 1^{\circ}\text{C/W}$  (typ.)  
(Ta = 25°C, with infinite heat sink)

The absolute maximum ratings of a semiconductor device are a set of specified parameter values, which must not be exceeded during operation, even for an instant. If any of these rating would be exceeded during operation, the device electrical characteristics may be irreparably altered and the reliability and lifetime of the device can no longer be guaranteed. Moreover, these operations with exceeded ratings may cause break down, damage and/or degradation to any other equipment. Applications using the device should be designed such that each absolute maximum rating will never be exceeded in any operating conditions. Before using, creating and/or producing designs, refer to and comply with the precautions and conditions set forth in this documents.

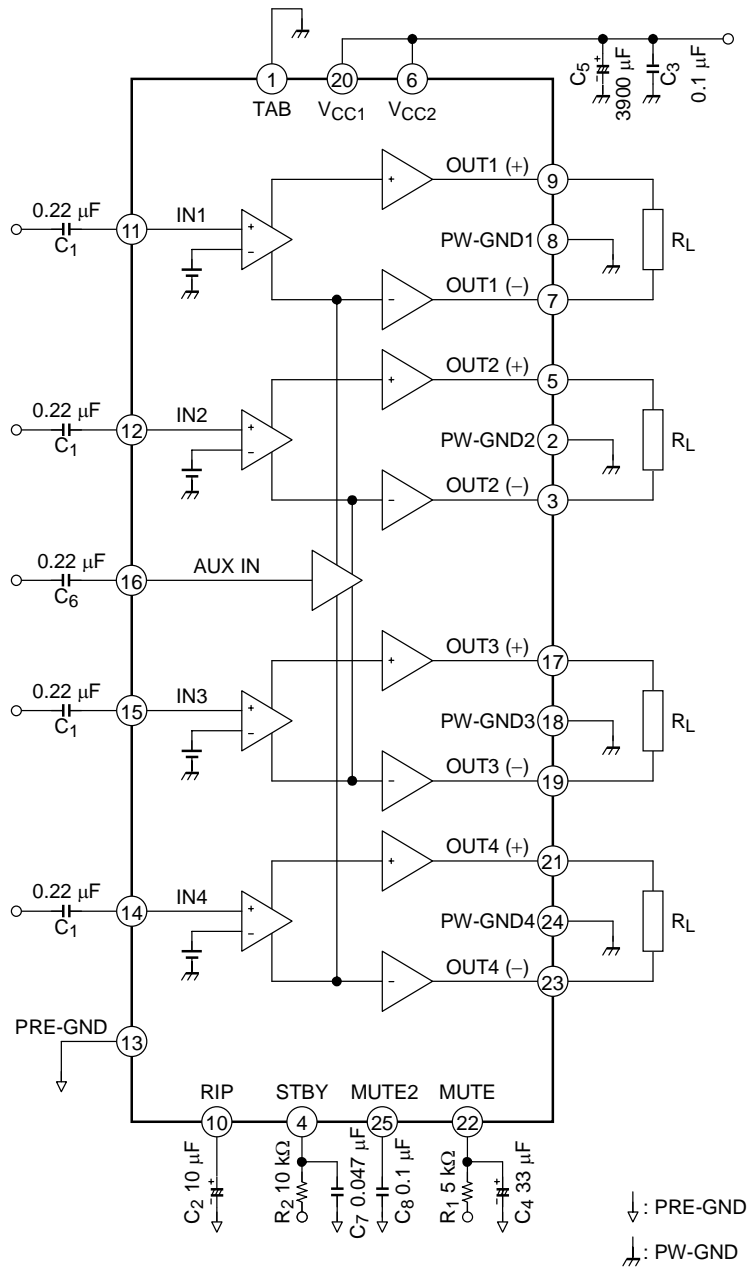
## Electrical Characteristics

(unless otherwise specified, V<sub>CC</sub> = 13.2 V, f = 1 kHz, R<sub>L</sub> = 4 Ω, Ta = 25°C)

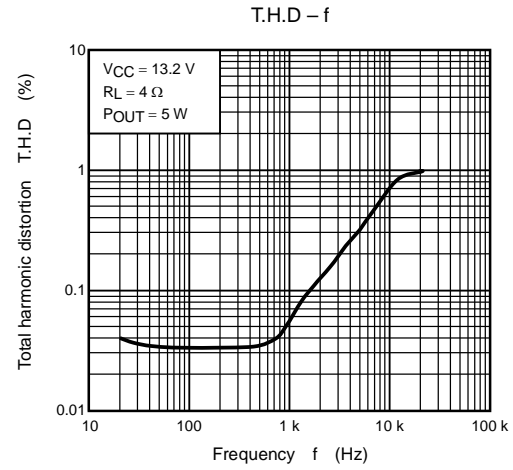
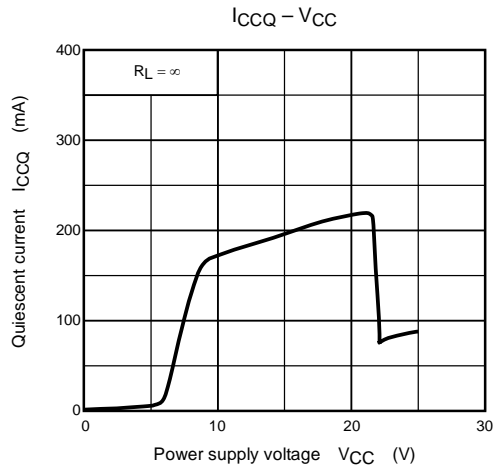
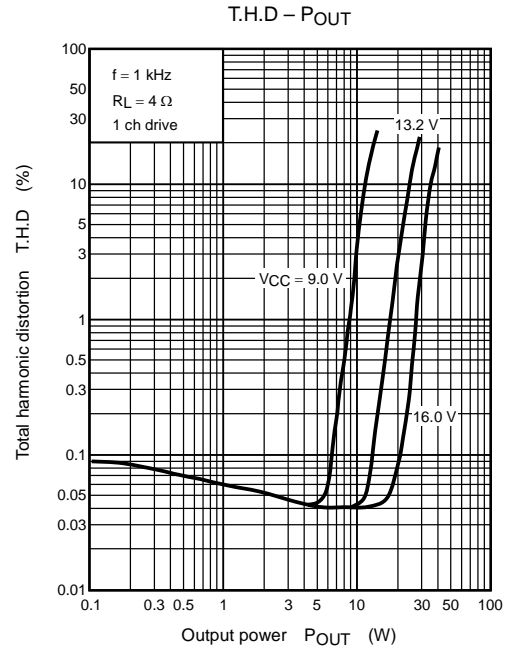
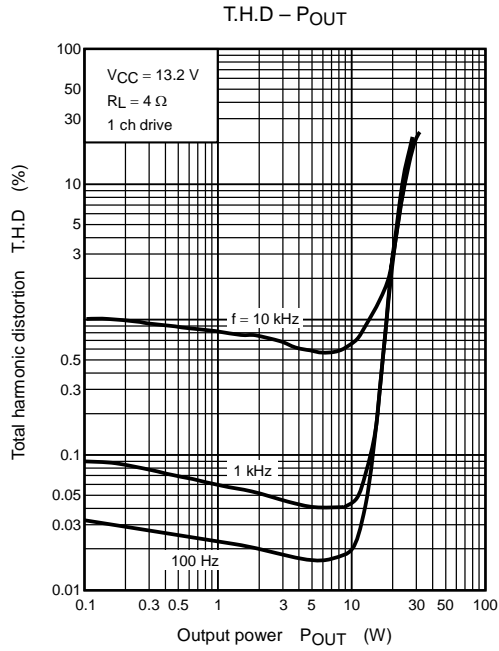
Characteristics	Symbol	Test Circuit	Test Condition	Min	Typ.	Max	Unit
Quiescent current	I <sub>CCQ</sub>	—	V <sub>IN</sub> = 0	—	200	400	mA
Output power	P <sub>OUT</sub> MAX (1)	—	V <sub>CC</sub> = 14.4 V, max Power	—	43	—	W
	P <sub>OUT</sub> MAX (2)	—	V <sub>CC</sub> = 13.7 V, max Power	—	40	—	
	P <sub>OUT</sub> (1)	—	V <sub>CC</sub> = 14.4 V, THD = 10%	—	28	—	
	P <sub>OUT</sub> (2)	—	THD = 10%	22	24	—	
Total harmonic distortion	THD	—	P <sub>OUT</sub> = 5 W	—	0.02	0.2	%
Voltage gain	G <sub>V</sub>	—	V <sub>OUT</sub> = 0.775 Vrms (0dBm)	24	26	28	dB
Voltage gain ratio	ΔG <sub>V</sub>	—	V <sub>OUT</sub> = 0.775 Vrms (0dBm)	-1.0	0	1.0	
Output noise voltage	V <sub>NO</sub> (1)	—	R <sub>g</sub> = 0 Ω, DIN45405	—	0.12	—	mVrms
	V <sub>NO</sub> (2)	—	R <sub>g</sub> = 0 Ω, BW = 20 Hz~20 kHz	—	0.10	0.35	
Ripple rejection ratio	R.R.	—	f <sub>rip</sub> = 100 Hz, R <sub>g</sub> = 620 Ω V <sub>rip</sub> = 0.775 Vrms (0dBm)	40	50	—	dB
Cross talk	C.T.	—	R <sub>g</sub> = 620 Ω V <sub>OUT</sub> = 0.775 Vrms (0dBm)	—	65	—	dB
Output offset voltage	V <sub>OFFSET</sub>	—	—	-150	0	+150	mV
Input resistance	R <sub>IN</sub>	—	—	—	90	—	kΩ
Stand-by current	I <sub>SB</sub>	—	Stand-by condition	—	2	10	μA
Stand-by control voltage	V <sub>SB</sub> H	—	Power: ON	3.0	—	V <sub>CC</sub>	V
	V <sub>SB</sub> L	—	Power: OFF	0	—	1.5	
Mute control voltage (Note5)	V <sub>M</sub> H	—	Mute: OFF	Open			—
	V <sub>M</sub> L	—	Mute: ON, R <sub>1</sub> = 10 kΩ	0	—	0.5	V
Mute attenuation	ATT M	—	Mute: ON, V <sub>OUT</sub> = 7.75 Vrms (20dBm) at Mute: OFF.	80	90	—	dB

Note 5: Muting function have to be controlled by open and low logic, which logic is a transistor, FET and μ-COM port of I<sub>MUTE</sub> > 50 μA ability. This means than the mute control terminal : pin 22 must not be pulled-up.

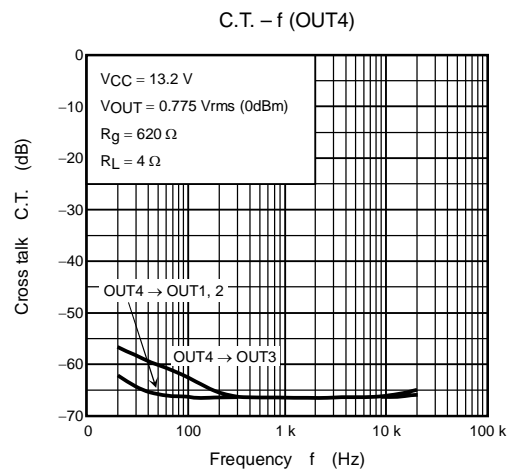
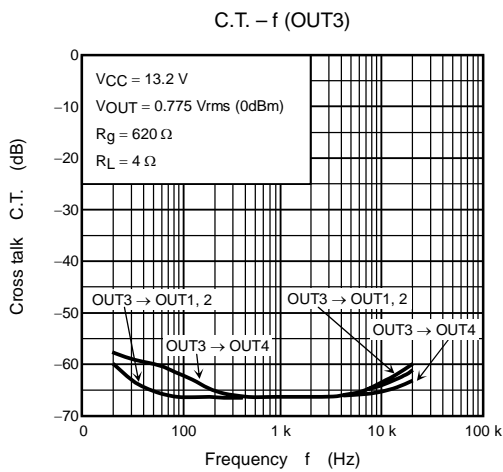
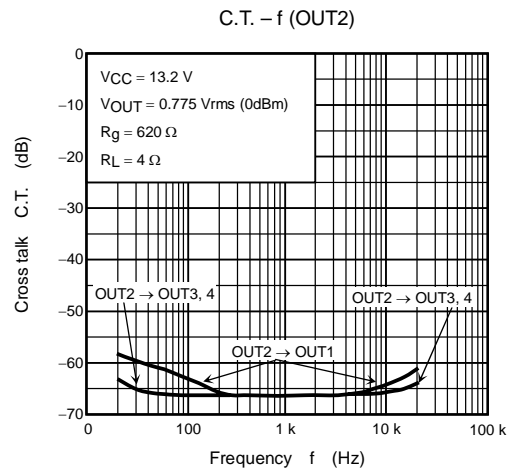
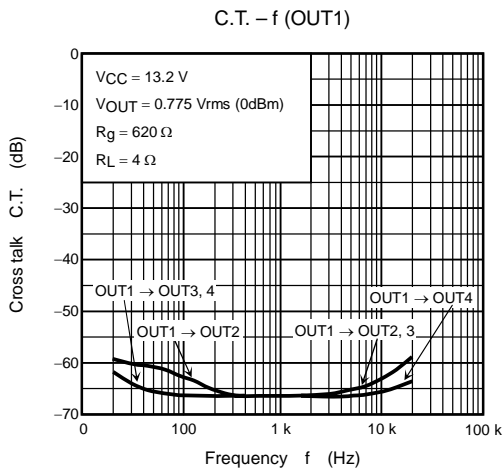
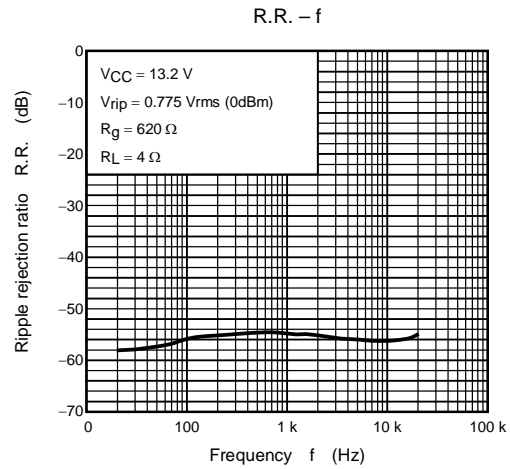
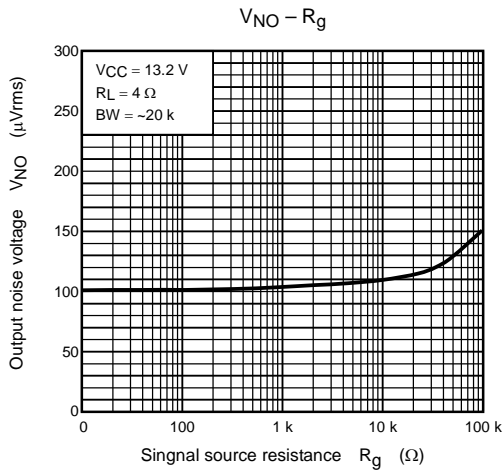
## Test Circuit

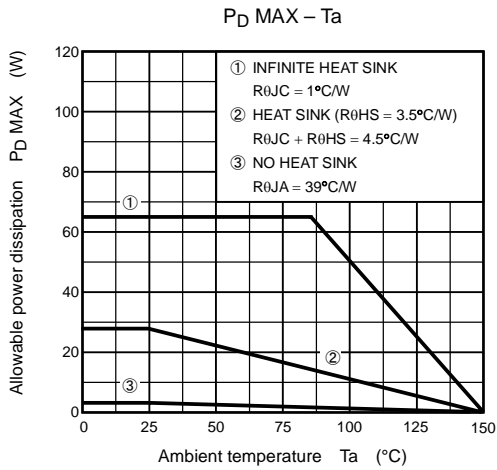
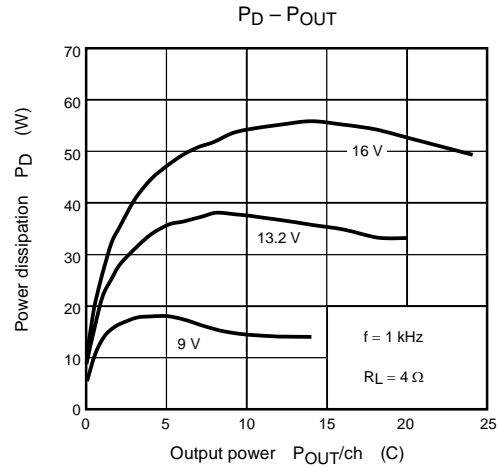
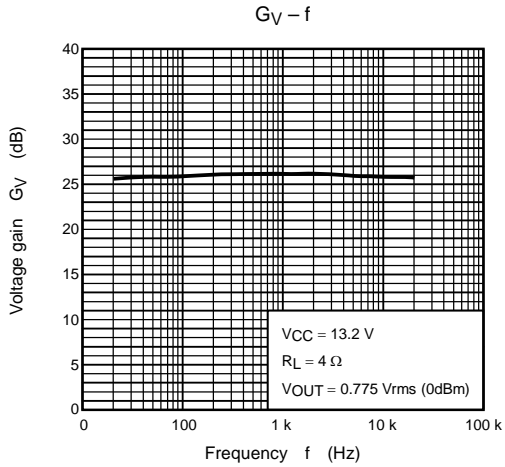


Components in the test circuits are only used to obtain and confirm the device characteristics.  
 These components and circuits do not warrant to prevent the application equipment from malfunction or failure.





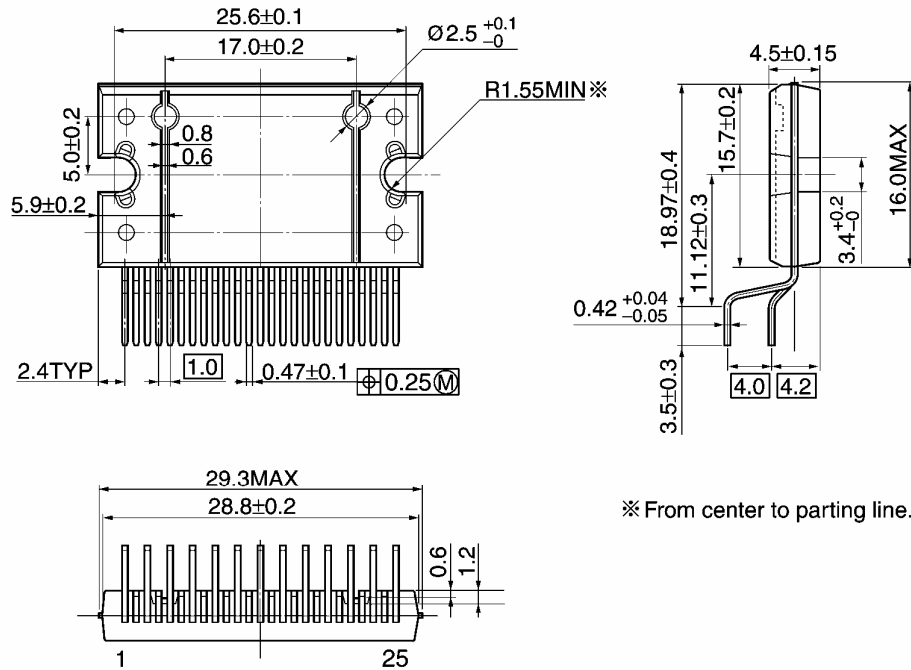




## Package Dimensions

HZIP25-P-1.00F

Unit: mm



※ From center to parting line.

Weight: 7.7 g (typ.)



- Use an appropriate power supply fuse to ensure that a large current does not continuously flow in case of over current and/or IC failure. The IC will fully break down when used under conditions that exceed its absolute maximum ratings, when the wiring is routed improperly or when an abnormal pulse noise occurs from the wiring or load, causing a large current to continuously flow and the breakdown can lead smoke or ignition. To minimize the effects of the flow of a large current in case of breakdown, appropriate settings, such as fuse capacity, fusing time and insertion circuit location, are required.
- If your design includes an inductive load such as a motor coil, incorporate a protection circuit into the design to prevent device malfunction or breakdown caused by the current resulting from the inrush current at power ON or the negative current resulting from the back electromotive force at power OFF. For details on how to connect a protection circuit such as a current limiting resistor or back electromotive force adsorption diode, refer to individual IC datasheets or the IC databook. IC breakdown may cause injury, smoke or ignition.
- Use a stable power supply with ICs with built-in protection functions. If the power supply is unstable, the protection function may not operate, causing IC breakdown. IC breakdown may cause injury, smoke or ignition.
- Carefully select external components (such as inputs and negative feedback capacitors) and load components (such as speakers), for example, power amp and regulator. If there is a large amount of leakage current such as input or negative feedback condenser, the IC output DC voltage will increase. If this output voltage is connected to a speaker with low input withstand voltage, overcurrent or IC failure can cause smoke or ignition. (The over current can cause smoke or ignition from the IC itself.) In particular, please pay attention when using a Bridge Tied Load (BTL) connection type IC that inputs output DC voltage to a speaker directly.
- **Over current Protection Circuit**  
Over current protection circuits (referred to as current limiter circuits) do not necessarily protect ICs under all circumstances. If the Over current protection circuits operate against the over current, clear the over current status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the over current protection circuit to not operate properly or IC breakdown before operation. In addition, depending on the method of use and usage conditions, if over current continues to flow for a long time after operation, the IC may generate heat resulting in breakdown.
- **Thermal Shutdown Circuit**  
Thermal shutdown circuits do not necessarily protect ICs under all circumstances. If the Thermal shutdown circuits operate against the over temperature, clear the heat generation status immediately. Depending on the method of use and usage conditions, such as exceeding absolute maximum ratings can cause the thermal shutdown circuit to not operate properly or IC breakdown before operation.
- **Heat Radiation Design**  
When using an IC with large current flow such as power amp, regulator or driver, please design the device so that heat is appropriately radiated, not to exceed the specified junction temperature (Tj) at any time and condition. These ICs generate heat even during normal use. An inadequate IC heat radiation design can lead to decrease in IC life, deterioration of IC characteristics or IC breakdown. In addition, please design the device taking into considerate the effect of IC heat radiation with peripheral components.
- **Installation to Heat Sink**  
Please install the power IC to the heat sink not to apply excessive mechanical stress to the IC. Excessive mechanical stress can lead to package cracks, resulting in a reduction in reliability or breakdown of internal IC chip. In addition, depending on the IC, the use of silicon rubber may be prohibited. Check whether the use of silicon rubber is prohibited for the IC you intend to use, or not. For details of power IC heat radiation design and heat sink installation, refer to individual technical datasheets or IC databooks.

## RESTRICTIONS ON PRODUCT USE

060116EBF

- The information contained herein is subject to change without notice. 021023\_D
- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.  
In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc. 021023\_A
- The TOSHIBA products listed in this document are intended for usage in general electronics applications (computer, personal equipment, office equipment, measuring equipment, industrial robotics, domestic appliances, etc.). These TOSHIBA products are neither intended nor warranted for usage in equipment that requires extraordinarily high quality and/or reliability or a malfunction or failure of which may cause loss of human life or bodily injury ("Unintended Usage"). Unintended Usage include atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, medical instruments, all types of safety devices, etc. Unintended Usage of TOSHIBA products listed in this document shall be made at the customer's own risk. 021023\_B
- The products described in this document shall not be used or embedded to any downstream products of which manufacture, use and/or sale are prohibited under any applicable laws and regulations. 060106\_Q
- The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by TOSHIBA for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of TOSHIBA or others. 021023\_C
- The products described in this document are subject to the foreign exchange and foreign trade laws. 021023\_E
- This product generates heat during normal operation. However, substandard performance or malfunction may cause the product and its peripherals to reach abnormally high temperatures.  
The product is often the final stage (the external output stage) of a circuit. Substandard performance or malfunction of the destination device to which the circuit supplies output may cause damage to the circuit or to the product. 030619\_R

About solderability, following conditions were confirmed

- Solderability
  - (1) Use of Sn-37Pb solder Bath
    - solder bath temperature = 230°C
    - dipping time = 5 seconds
    - the number of times = once
    - use of R-type flux
  - (2) Use of Sn-3.0Ag-0.5Cu solder Bath
    - solder bath temperature = 245°C
    - dipping time = 5 seconds
    - the number of times = once
    - use of R-type flux